

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	N/A	Silicon Carbide (SiC)	409-21-2	0.12	100.0	2.32
Subtotal				0.12	100	2.32
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.1	100.0	1.96
Subtotal				0.1	100	1.96
Solder Wire	Lead alloy	Tin (Sn)	7440-31-5	0	2.0	0.02
	Lead alloy	Silver (Ag)	7440-22-4	0	2.5	0.02
	Lead alloy	Lead (Pb)	7439-92-1	0.05	95.5	0.93
	Subtotal		0.05	100	0.97	
Post-plating	Lead alloy	Tin (Sn)	7440-31-5	0.75	100.0	15
Subtotal				0.75	100	15
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02	0.03	0.43
	Copper alloy	Iron (Fe)	7439-89-6	0.07	0.1	1.42
	Copper alloy	Copper (Cu)	7440-50-8	70.19	99.67	1412.32
	Copper alloy	Silver (Ag)	7440-22-4	0.14	0.2	2.83
	Subtotal		70.42	100	1417	
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	1.86	6.5	37.38
	Polymer	Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic)	29690-82-2	4.57	16.0	92
	Filler	Silica fused	60676-86-0	20.29	71.0	408.25
	Flame retardant	Metal hydroxide		1.86	6.5	37.38
	Subtotal		28.58	100	575.01	
Total				100.02	100	2012.26

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